

On electroadhesive layer jamming structures

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Introduction

Variable stiffness is a useful function for living creatures to survive and adapt in unknown and changing environments, and is needed for morphingload bearing tasks in our daily life. Jamming is a common variable stiffness mechanism and layer jamming is a popular variable stiffness structure. Here we present a fundamental study of parallel electroadhesive layer jamming structures under different loading conditions, and compare the theoretical and experimental deflection-force curves. The results may provide helpful insights towards their practical applications.

Objective

Method

We aim to present a comprehensive and We use the Euler-Bernoulli beam theory and consider slip between layers by integrating the experimentally validated theoretical variable Maxwell stress tensor into the model.

flexible stiffness parallel (a) models of

electroadhesive structures.

There are three phases during the structural bending:

1) pre-slip or adhesion phase: the whole structure is electrically f_{x} bonded in a stable way when $\tau_{max}(x, y) \le \tau_f$; 2) partial-slip or transition phase: the whole structure has partial layer slips when $\tau_{\min}(x, y) < \tau_f \leq \tau_{\max}(x, y)$; 3) full-slip phase: layer slip occurs in the whole structure when $\tau_{\min}(x, y) > \tau_f$. τ_f is the electroadhesive shear stress between layers. $\tau_{\min}(x, y)$ and $\tau_{\max}(x, y)$ represent the maximum and minimum shear stress at the position where the layers are in contact with each other respectively, when we assume that the multilayer structure is a whole.



Fig. 2 Schematic diagram of the variable stiffness flexible parallel electroadhesive physical Fig. 1 A flexible parallel electroadhesive that model: (a) 3D configuration under no load, (b) 2D configuration under no load (red arrows) change its bending stiffness under denote electroadhesive forces), and (c) 2D configuration under a central concentrated force (F is can different voltages (such as 1 and 5 kV). f the load and L is the three-point bending support span length).

Analytical modelling

Experimental validation

The theoretical deflection-force curves of three-point We derive variable stiffness models of three three-point bending, cantilever beam bending under tip concentrated forces, and cantilever beam bending under uniformly bending and cantilever beam bending under tip concentrated force all agreed relatively well with the experimental curves. distributed forces.



Conclusion

- three-point bending and cantilever beam bending under tip concentrated forces only have pre-slip and full-slip, whereas cantilever beam bending under uniformly distributed forces has an additional partial-slip which can be used for stiffness modulation;
- the reason leads to partial-slips comes from changed shear force distributions inside structures; so for any electrostatic jamming structures that are subjected to area loads, partial-slips will occur;
- the stiffness during the pre-slip stage is four times larger than the stiffness in the full-slip stage;
- increasing the voltage, dielectric permittivity and coefficient of friction can elongate the pre-slip stage, thus enhancing the structural load capability.

(b) Comparison between different samples and (b) theoretical and Comparison between the the experimental deflection- theoretical and experimental force curve of the three- deflection-force curve of the point beam bending case. cantilever beam bending under tip concentrated forces case.

Future work

- experimental validation of the variable stiffness model of cantilever beam bending under uniformly distributed forces;
- variable stiffness modeling of multi-layer flexible electro-adhesive jamming structures.

Y. Yuan, F. Li, J. Guo, L. Liu, Y. Liu, and J. Leng, On variable stiffness of flexible parallel electroadhesive structures, *Smart Materials and Structures*, 32(5), 2023, pp. 055004 (doi: 10.1088/1361-665X/acbd01).